

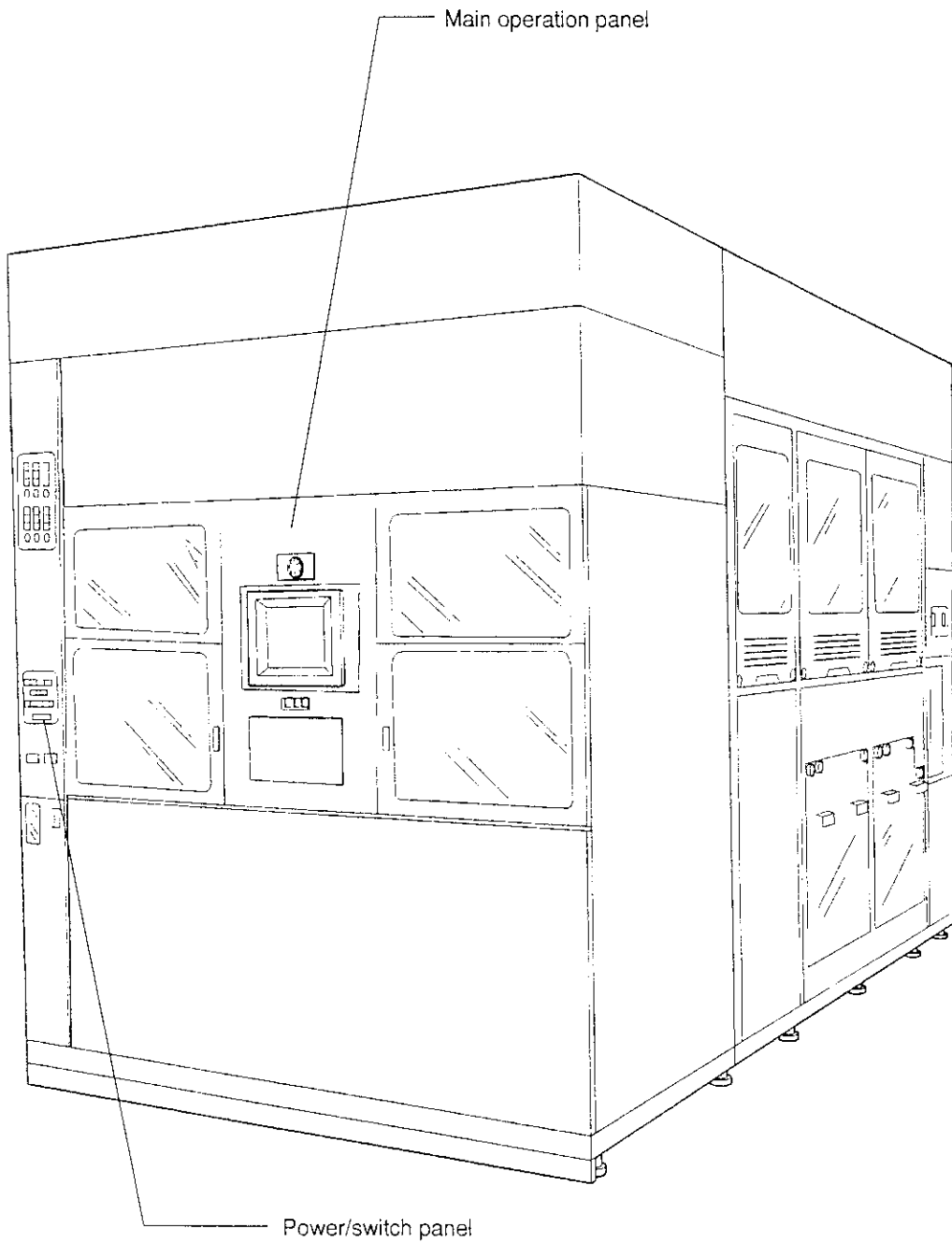
## 1 System configuration

The equipment is configured as shown below. However, the configuration may differ depending on the specifications.

Top view of the equipment

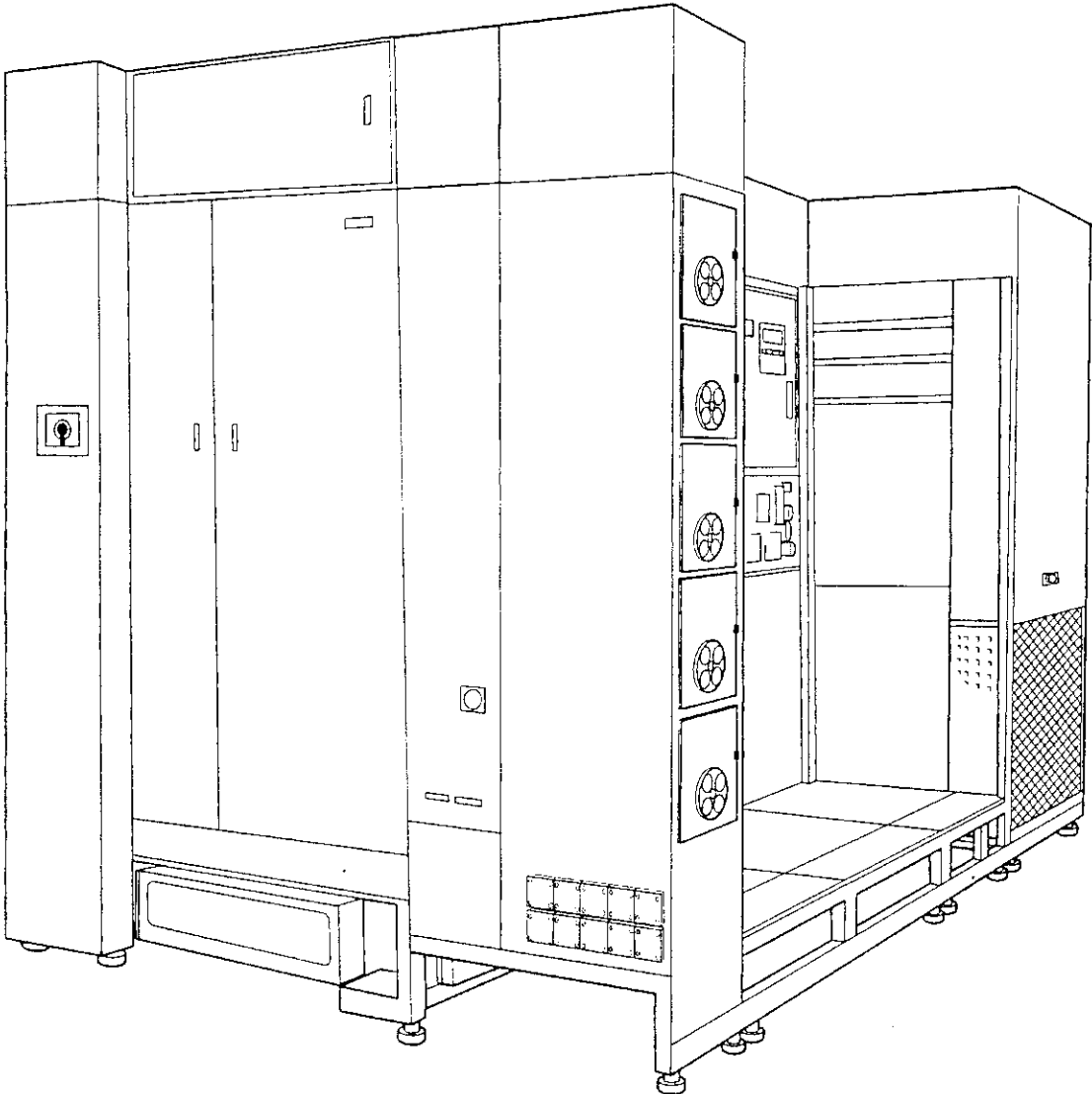
Front (operation) side	ST1/2	CTR	CCL	Maintenance area				CSB 1~5
	ST3/4			CTC	LPD	LFS1		
			ONB1		CHB1	ONB2	CHB2	
	ST5/6		WTR					

Front



Caution: Since the above overview shows the standard specifications, equipment with options or customized specifications may differ from this illustration.

Rear



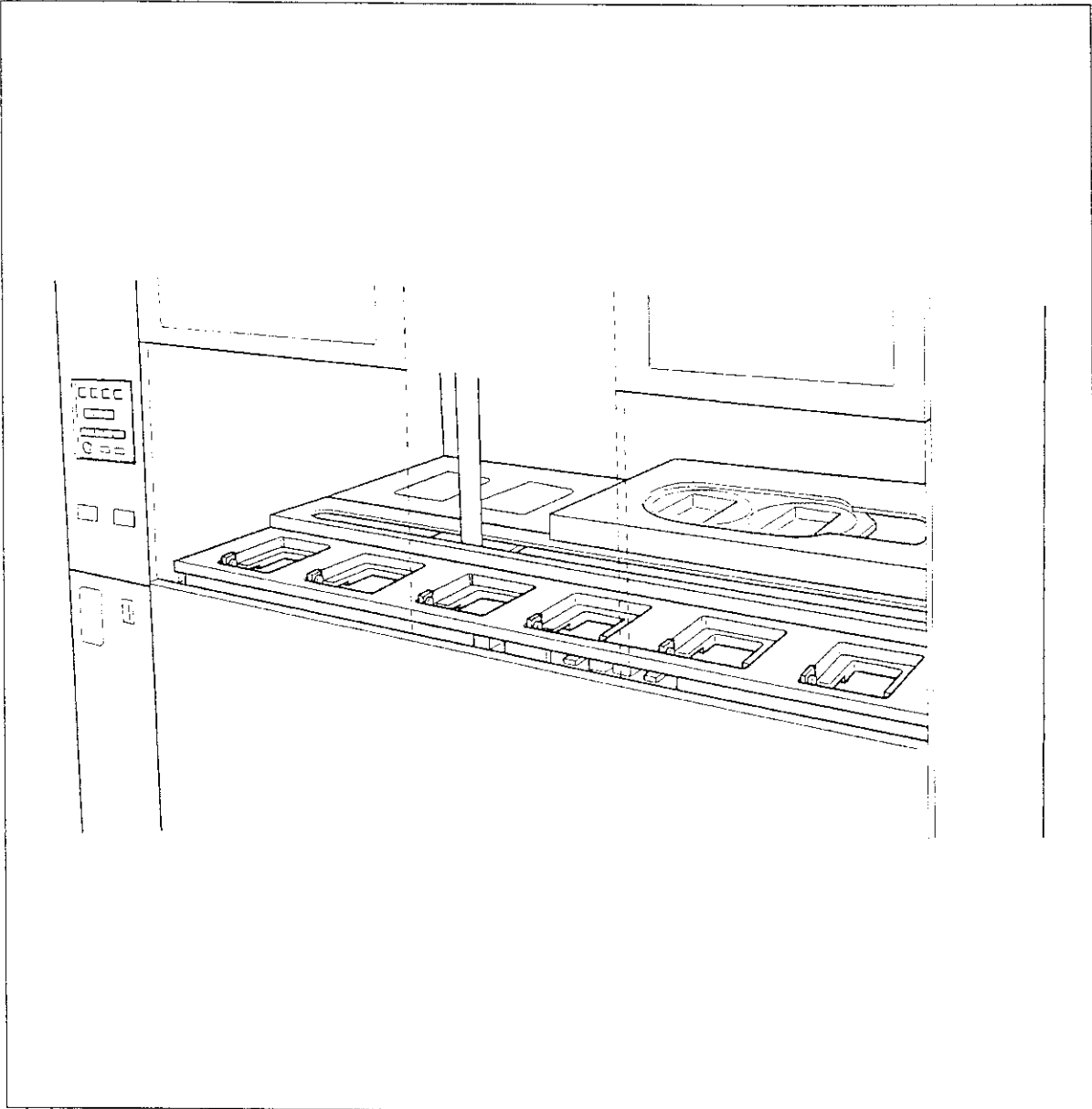
Caution: Since the above overview shows the standard specifications, equipment with options or customized specifications may differ from this illustration.

## 2 Function of the various modules

This section describes each module function.

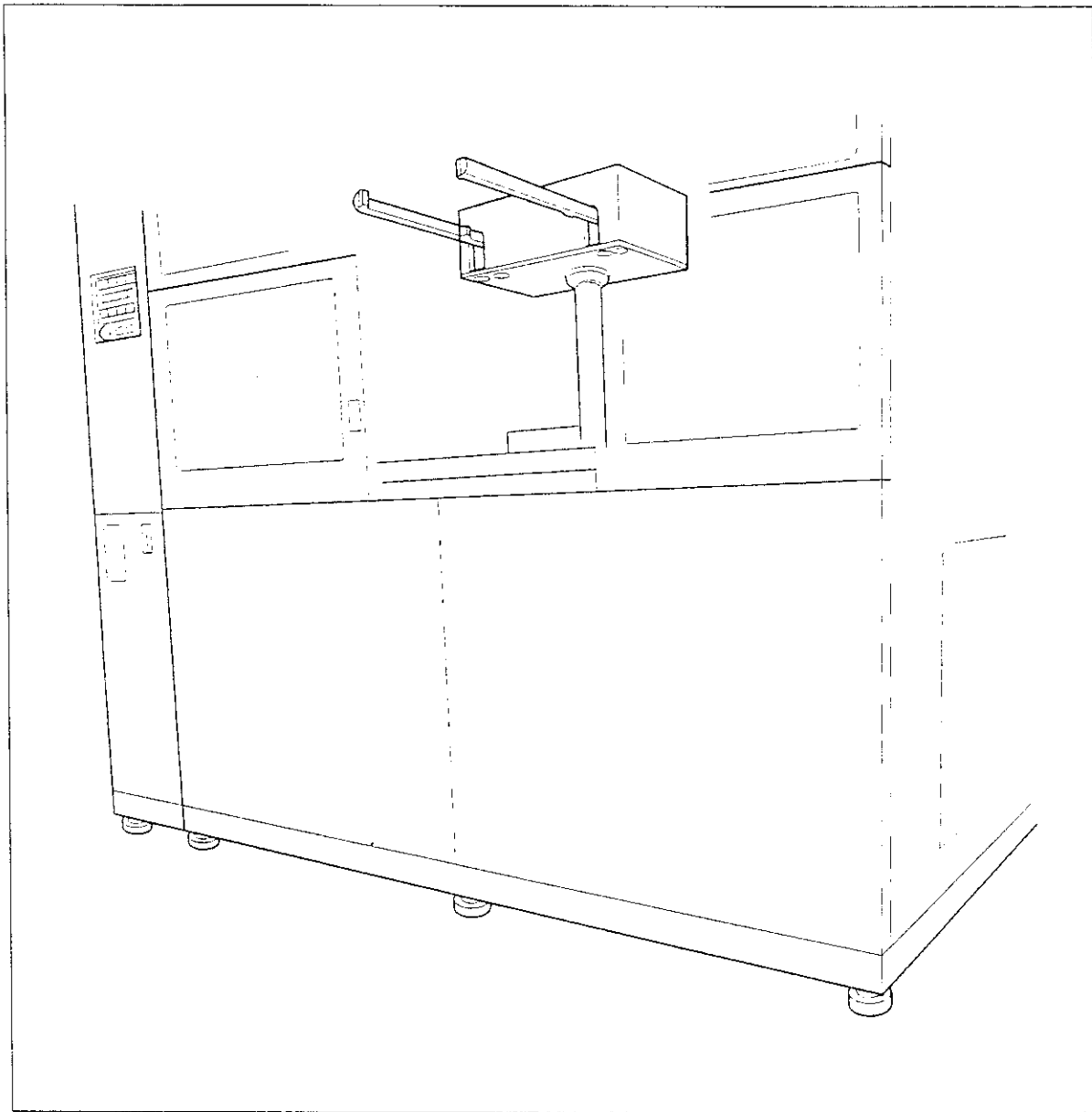
### 2.1 Stage (ST)

This module delivers and discharges lot. Cassettes holding wafers are placed on this module.



## 2.2 Cassette transfer module (CTR)

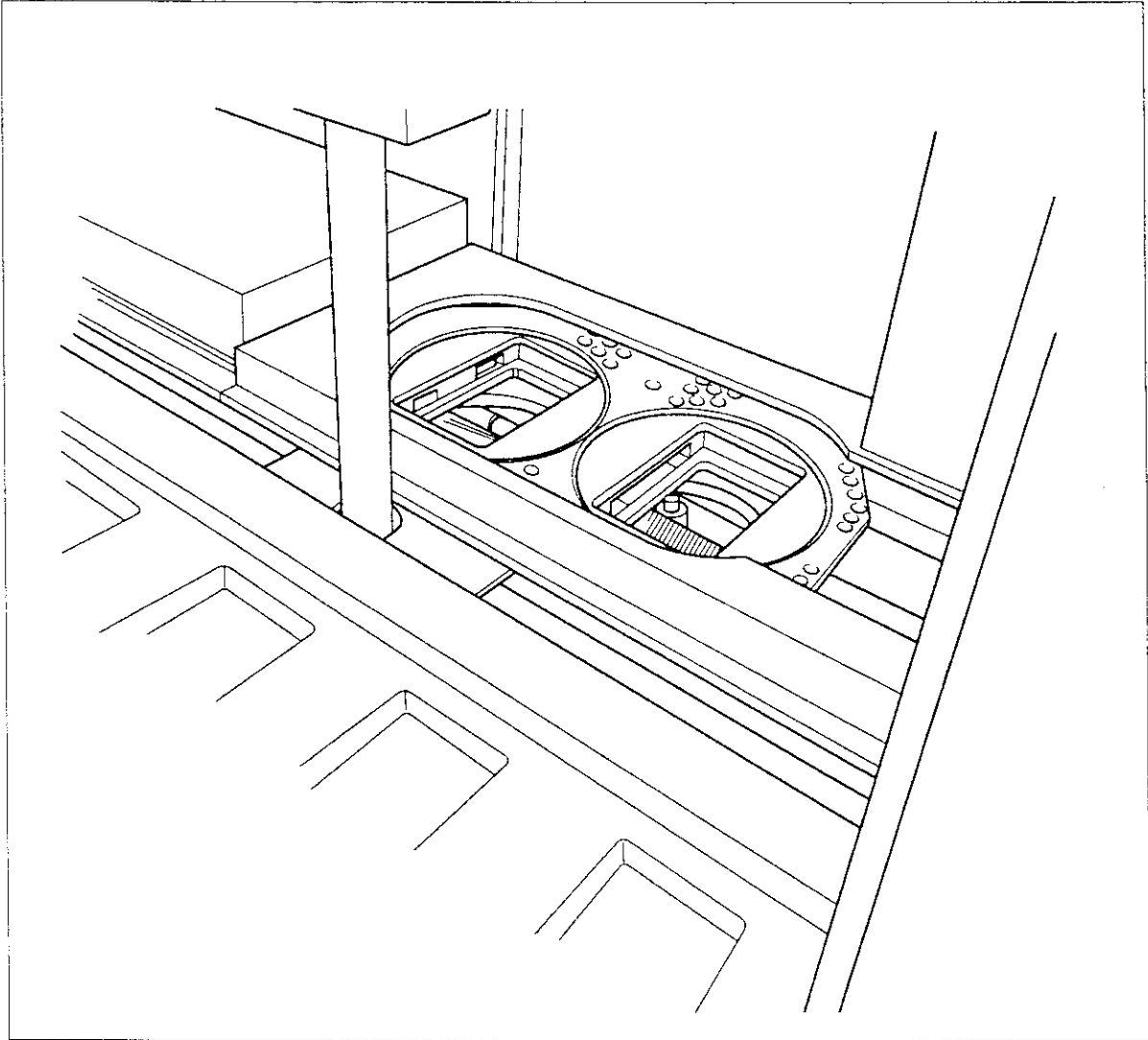
This module transfers cassettes between the ST and the CTC, and the CTC and the CCL.



### 2.3 Wafer transfer module (CTC)

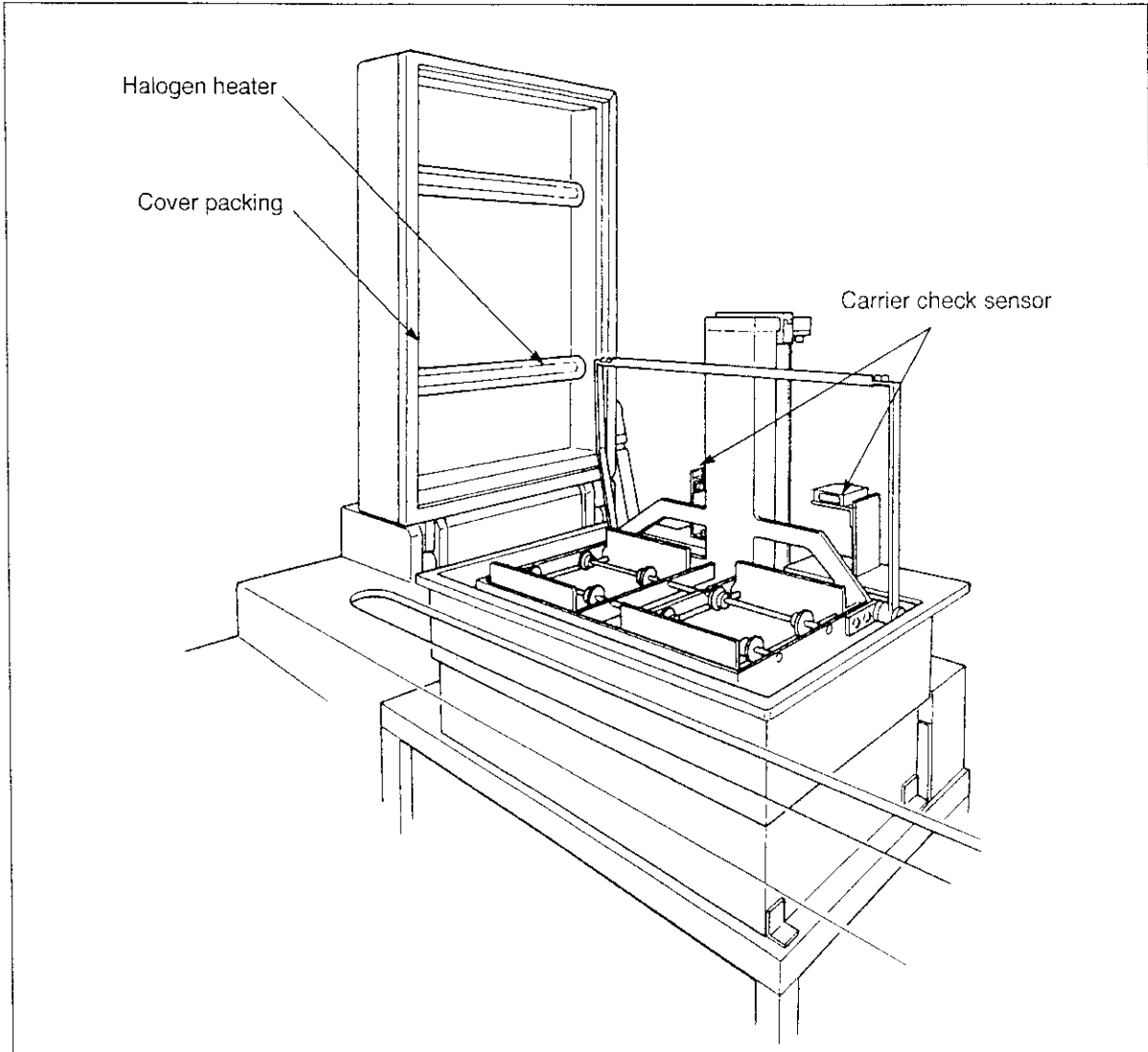
This module takes wafers out of a cassette and transfers them to the WTR. Also it receives the processed wafers from the WTR and stores them in a cassette.

Switching from the normal pitch to the half pitch or vice versa is performed at this stage.



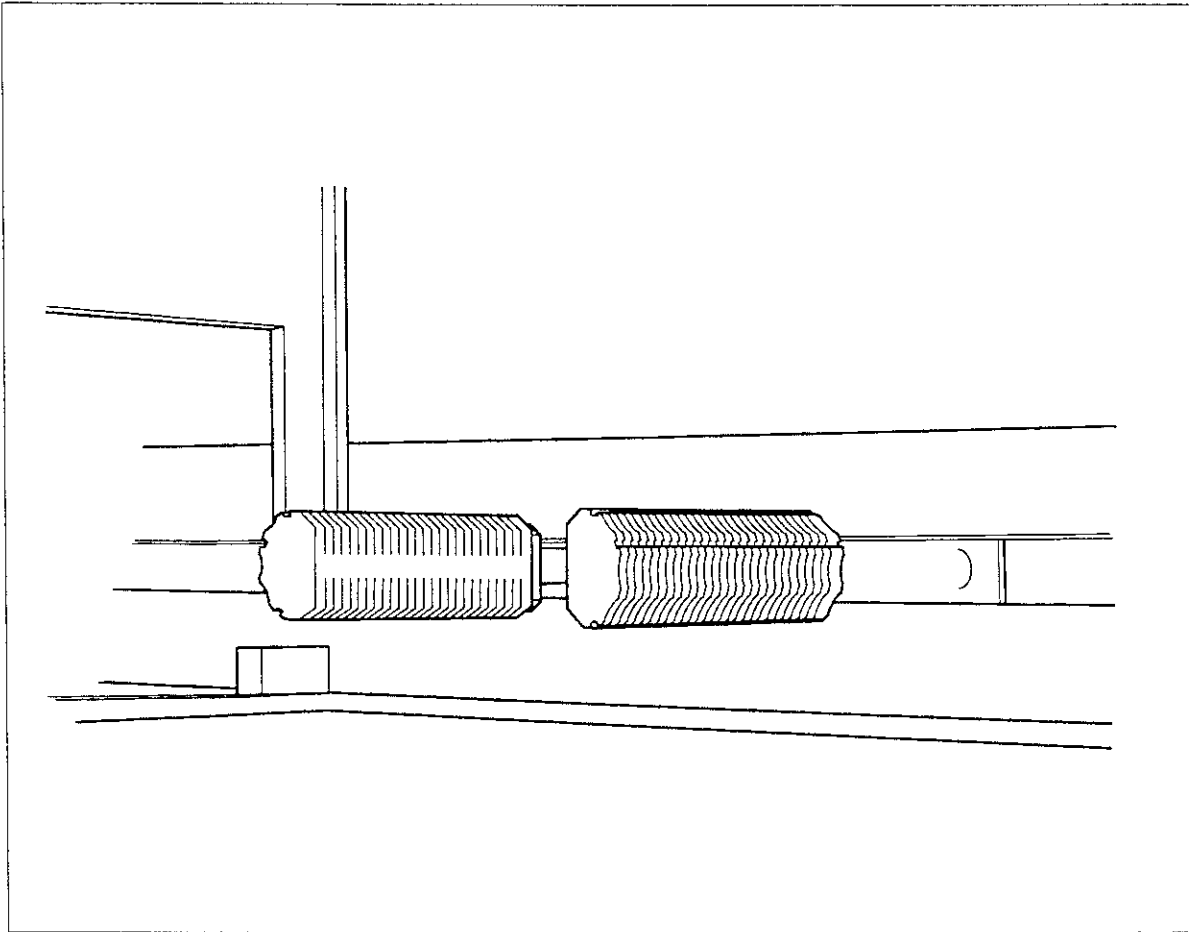
## 2.4 Carrier cleaning bath (CCL)

Empty cassettes will be cleaned and dried in this processing bath.



## 2.5 Wafer transfer module (WTR)

The WTR transfers wafers from the CTC to the lifter slider or the LPD lifter, or transfers the processed wafers to the CTC.





## 2.6 Processing bath (ONB)

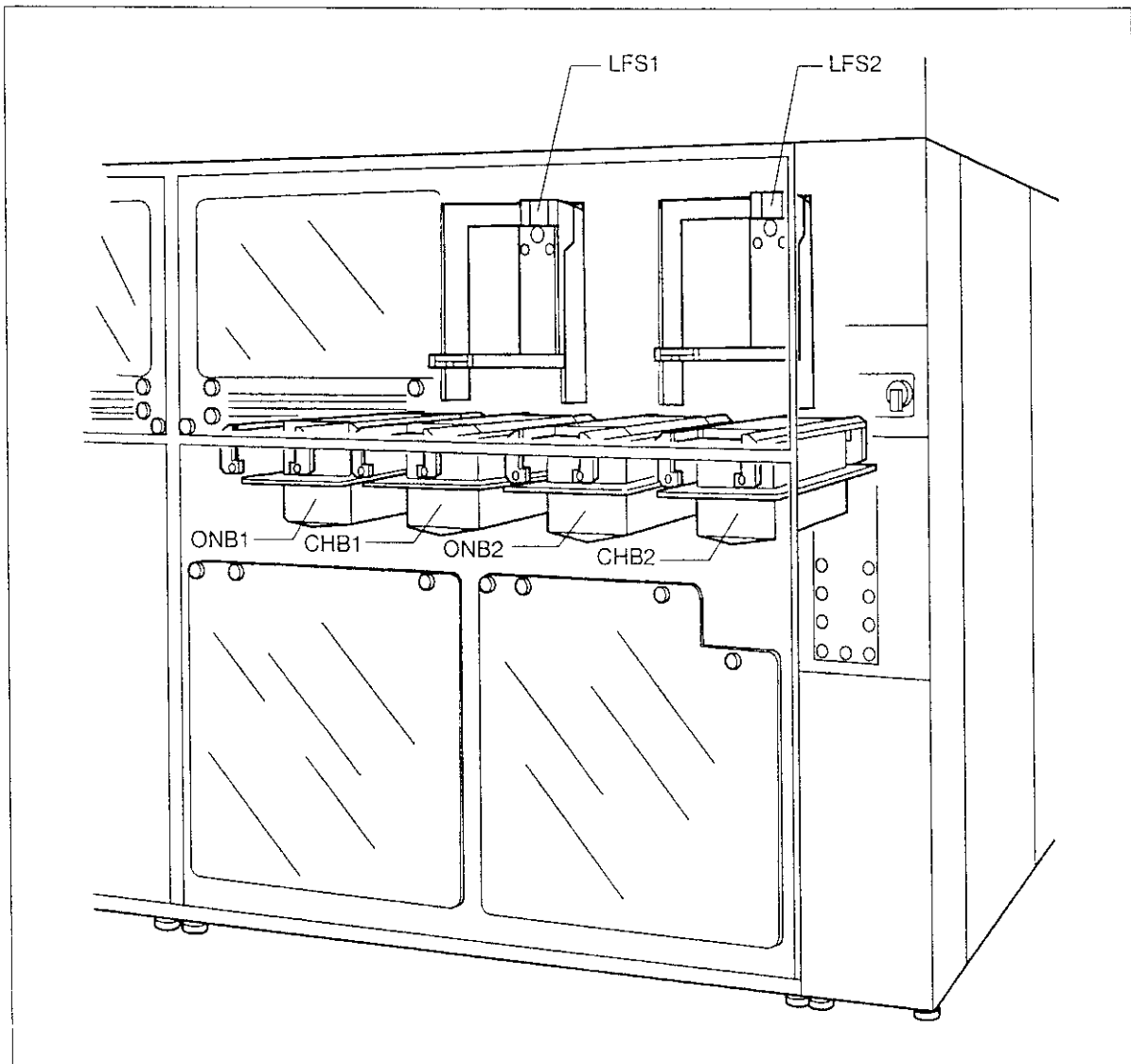
This module mixes a chemical and DI water at a specified mixing ratio and performs the wafer cleaning process in the processing bath. It rinses the processed wafers with DI water.

## 2.7 Chemical processing bath (CHB)

This modules etches wafers, strips photoresist from wafers, or removes particles from wafers using various type of chemicals.

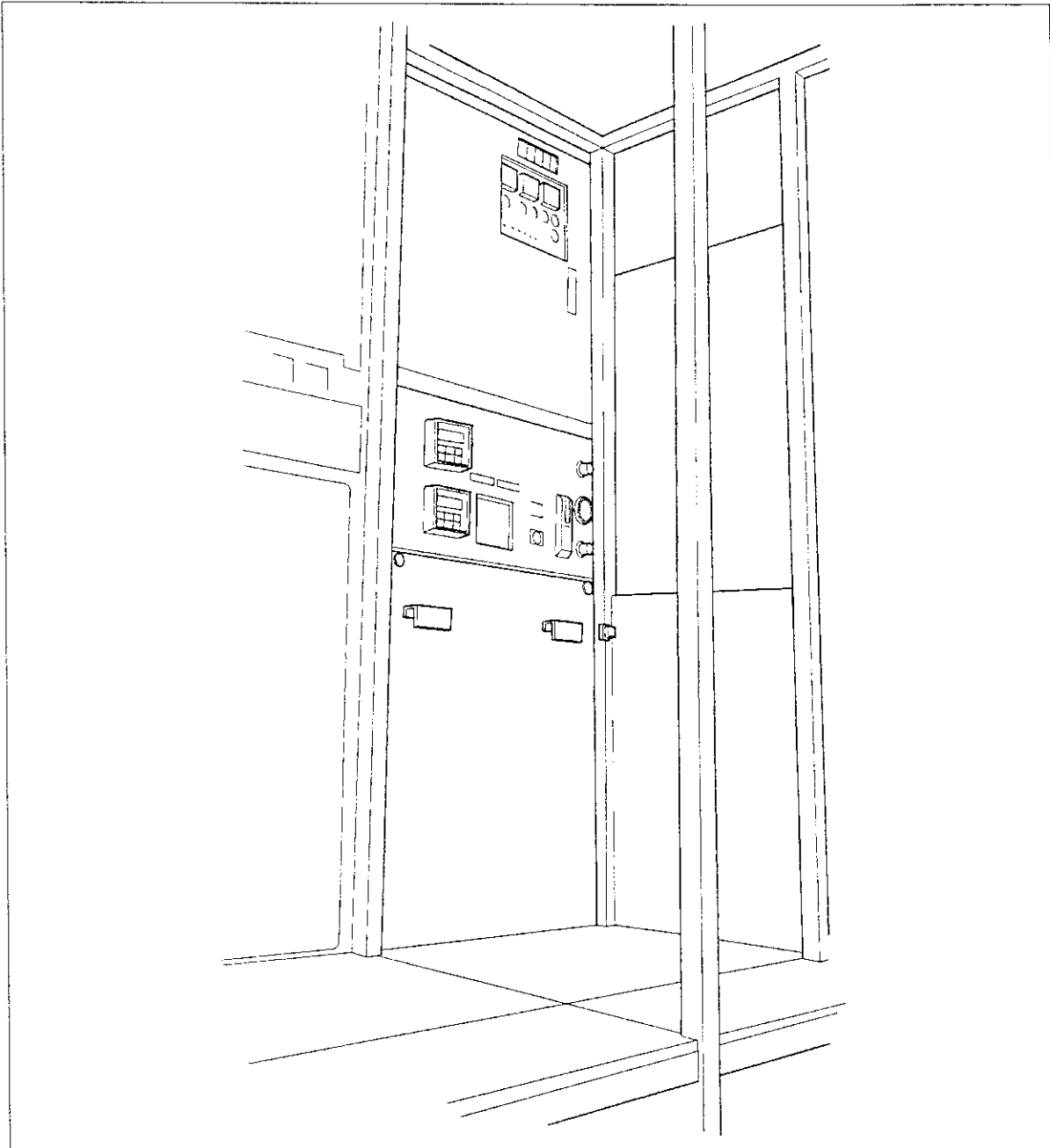
## 2.8 Lifter (LFS)

This module delivers and discharges wafers to each processing bath.



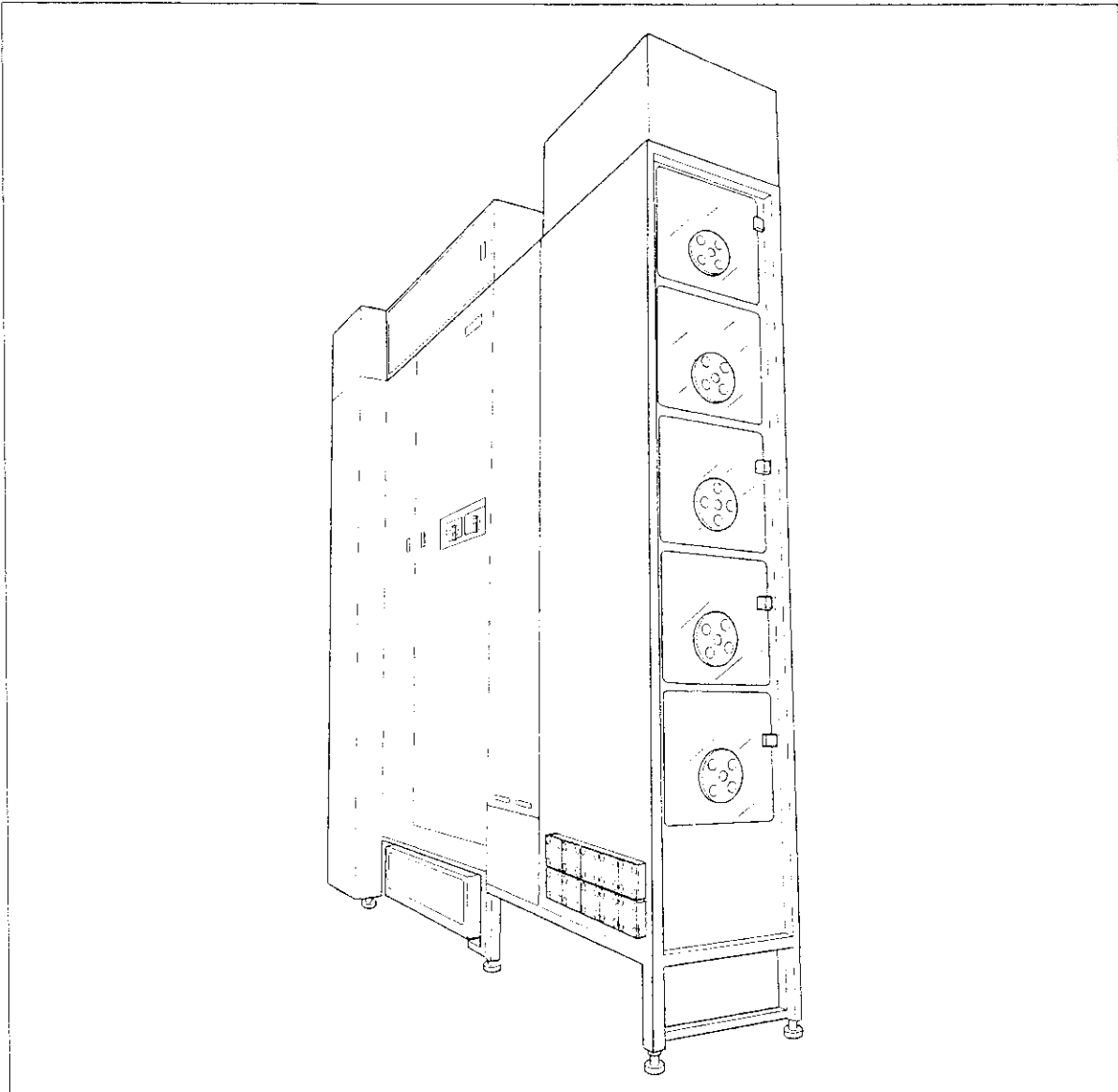
## 2.9 Low pressure dryer (LPD)

This module cleans wafers and dries them with low pressure air while purging N<sub>2</sub> and IPA.



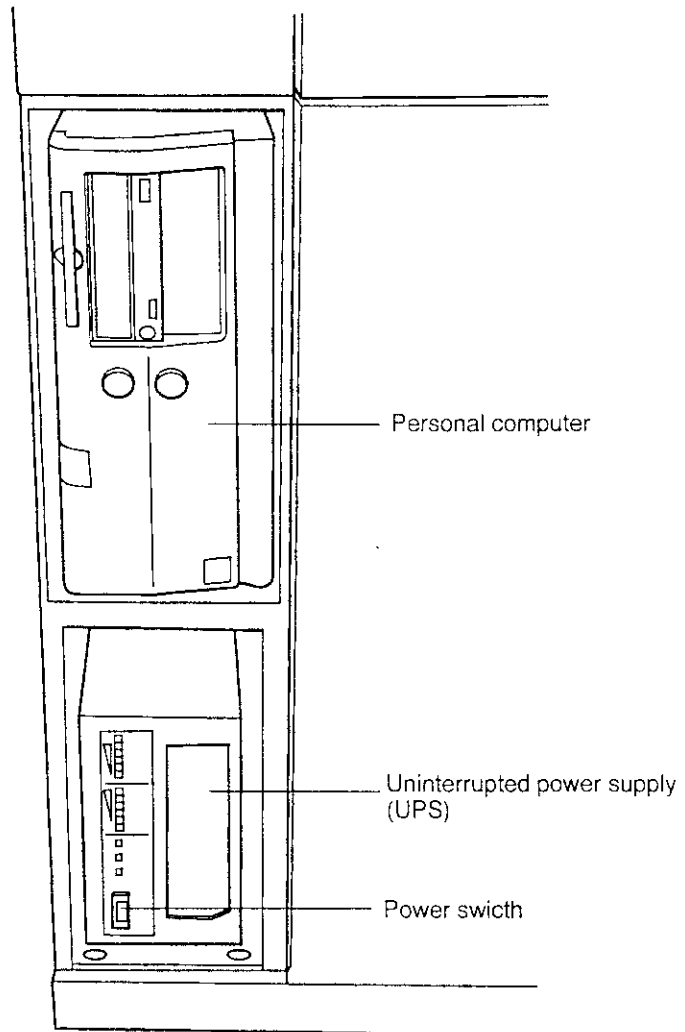
## 2.10 Chemical supply module (CSB)

This module supplies chemicals to the processing bath.



## 2.11 Personal computer unit

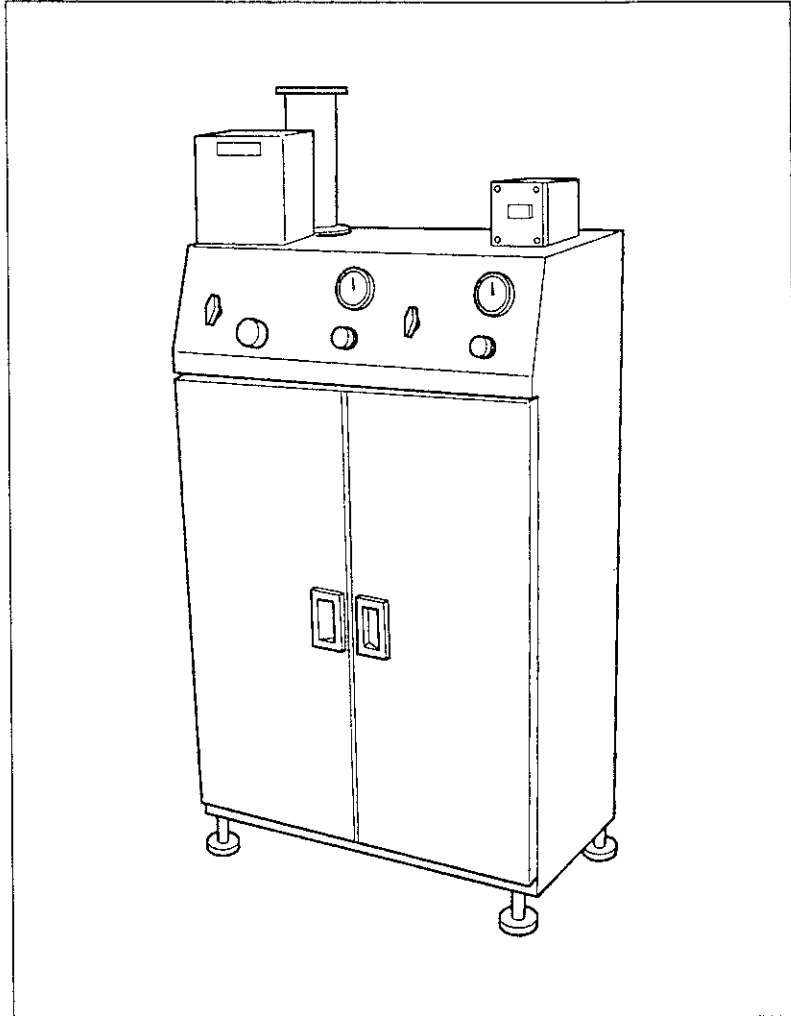
This unit controls the equipment and composed of a personal computer, keyboard, display monitor, and the uninterruptured power supply.



## 2.12 External units

### ■ IPA supply unit

This unit supplies IPA to the LPD bath.



■ CSU

This unit supplies chemicals to the CSB (or the processing bath).

